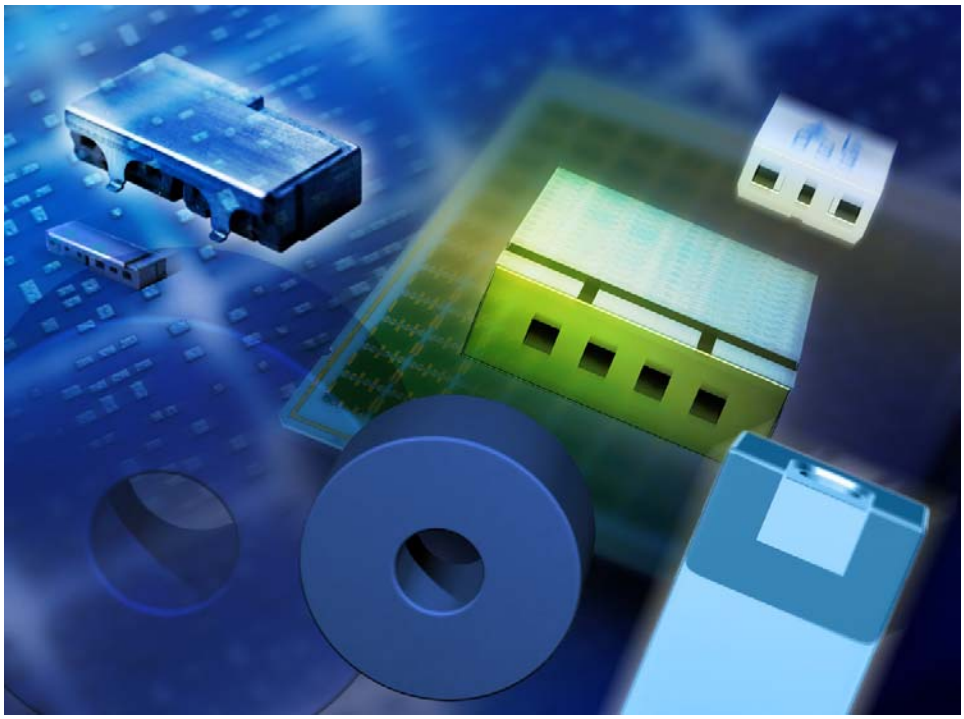
EPCOS

Microwave Ceramics and Modules	Product type
3-Pole Filter for PCS RX	**B69813N1967Z460**

Preliminary Datasheet



Features

- SMD filter consisting of coupled resonators with stepped impedances
- (NdBa)TiO_3 (ε_r = 88 / TC_f =0±10 ppm/K) with a coating of copper (10µm) and tin (>5µm)
- Excellent reflow solderability, no migration effect due to copper/tin metallization

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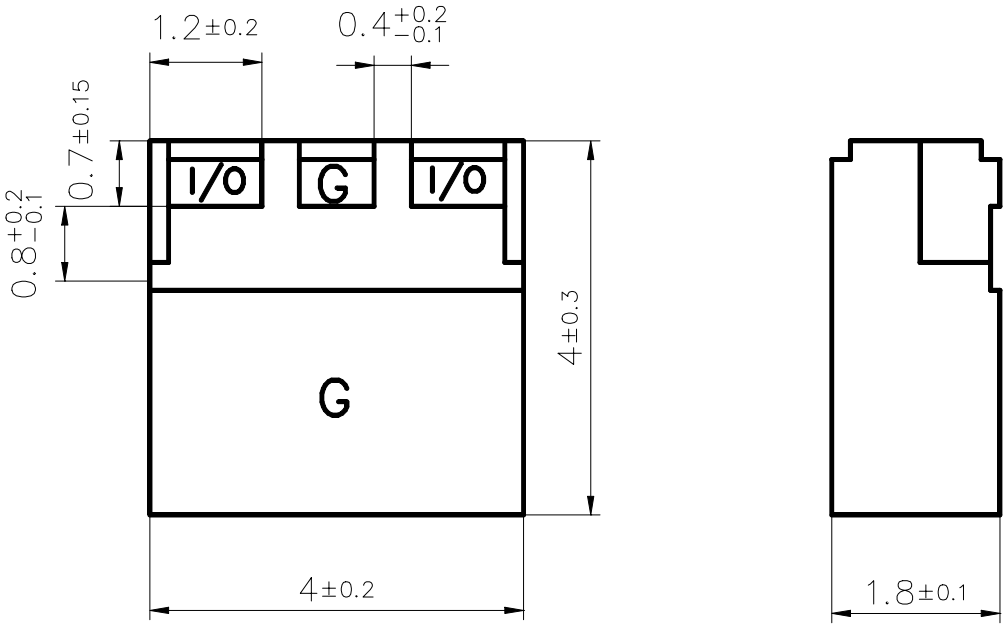
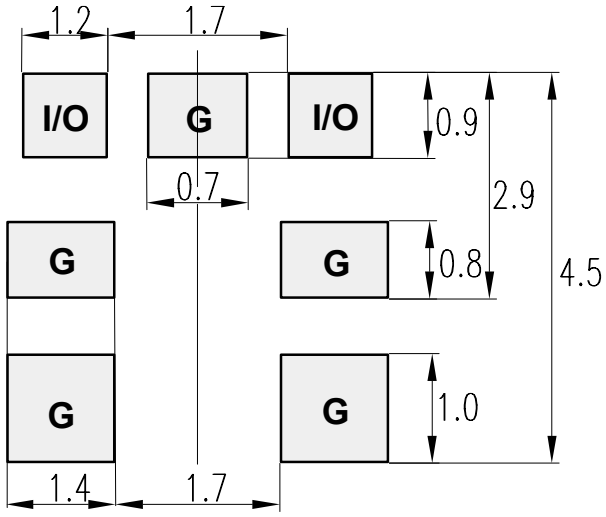
Component drawing



View from below onto the solder terminals and view from beside

Recommended footprint



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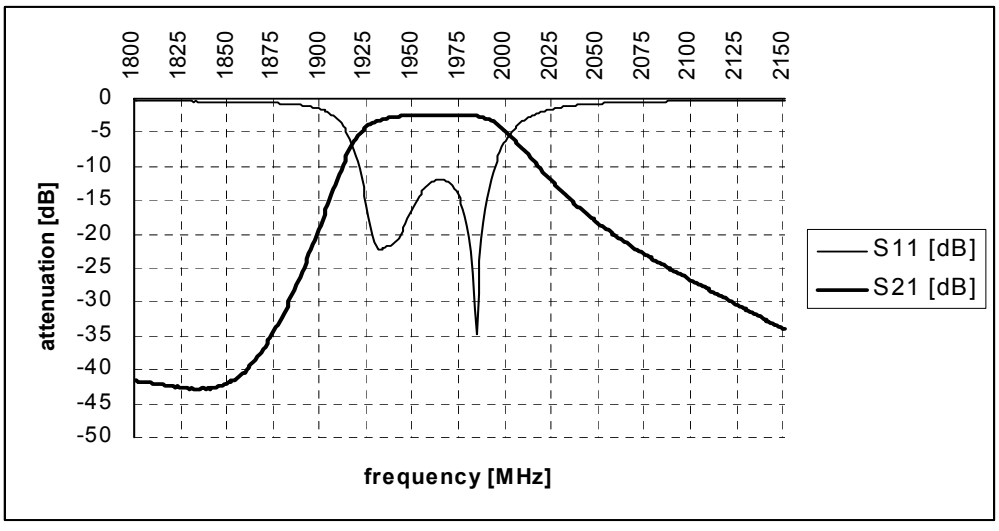
Characteristics (items marked with * must still be correlated to customer print, top surface may have additional contact to ground)

		min.	typ.	max.	
Center frequency	f_C	-	1960,0	-	MHz
Insertion loss	α_{IL}		2.9	3.4*	dB
Passband	B	60			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$		1.2	1.5	dB
Power				15	dBm
Standing wave ratio (S11, S22)	SWR		1.5	2.2	
Impedance	Z		50		Ω
Attenuation	α				
at DC to 1830 MHz		38	40		dB
at 1830 to 1910 MHz		11*			dB
at 2010 to 2020 MHz		7.5*			dB
at 2020 to 2070 MHz		10*			dB
at 2070 to 3000 MHz		18*			dB
at 3000 to 5000 MHz		15			dB

Maximum ratings

IEC climatic category (IEC 68-1)		- 40 / + 90/56	
Storage temperature	T_{st}	- 40 / + 85	
Operating temperature	T_{op}	- 20 / + 80	°C

Typical passband characteristic



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Processing information

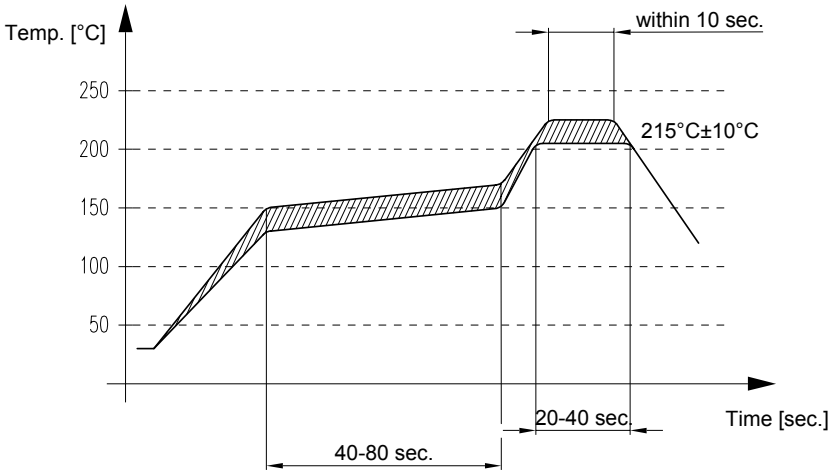
ZNr.: 452 (FILT95_2)

- Wettability to IEC 68-2-58: ≥ 75% (after aging)

Soldering requirements

Soldering type	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	°C °C

Recommended soldering conditions (infrared):



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Delivery mode

- Blister tape acc. to IEC 286-3, polystyrol, grey
- Pieces/ tape: 3000

t.b.d.

S2P3.DOC